ON Semiconductor

10/15/2019

Base Part	**FQP4N90C**		
Orderable Part	**FQP4N90C**	**Total weight (mg)**	**2030.183**

Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	2.81	Silicon (Si)	7440-21-3	100
Die Attach Solder	1.111	Silver (Ag)	7440-22-4	2.5
		Lead (Pb)	7439-92-1	92.5
		Tin (Sn)	7440-31-5	5
Lead Frame	1492.122	Nickel (Ni)	7440-02-0	0.01
		Iron (Fe)	7439-89-6	0.1
		Copper (Cu)	7440-50-8	99.86
		Phosphorus (P)	7723-14-0	0.03
Mold Compound-Black	518.4	Brominated Bisphenol A Diglycidyl Ether	40039-93-8	2
		Ortho Cresol Novolac Resin	29690-82-2	8.5
		Antimony Trioxide (Sb2O3)	1309-64-4	1.5
		Carbon Black (C)	1333-86-4	0.5
		Fused Silica (SiO2)	60676-86-0	80
		Silica (SiO2)	14464-46-1	1
		Phenolic Resin (Novolac)	9003-35-4	6.5
Plating	13.3	Tin (Sn)	7440-31-5	100
Wire Bond - Al	2.44	Aluminum (Al)	7429-90-5	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF